

150V N-Ch Power MOSFET
Feature

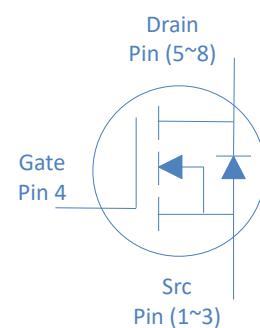
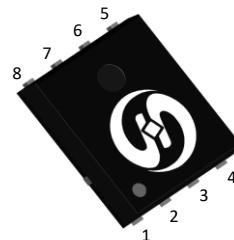
- ◊ High Speed Power Switching
- ◊ Enhanced Body diode dv/dt capability
- ◊ Enhanced Avalanche Ruggedness
- ◊ 100% UIS Tested, 100% Rg Tested
- ◊ Lead Free, Halogen Free

V_{DS}	150	V	
$R_{DS(on),typ}$	$V_{GS}=15V$	6	$m\Omega$
$R_{DS(on),typ}$	$V_{GS}=10V$	6.8	$m\Omega$
I_D (Silicon Limited)	93	A	
I_D (Package Limited)	60	A	

Application

- ◊ Synchronous Rectification in SMPS
- ◊ Hard Switching and High Speed Circuit
- ◊ DC/DC in Telecoms and Industrial

Part Number	Package	Marking
HGN065N15M6	DFN5*6	GN065N15M6

DFN5x6

Absolute Maximum Ratings at $T_j=25^\circ C$ (unless otherwise specified)

Parameter	Symbol	Conditions	Value	Unit
Continuous Drain Current (Silicon Limited)	I_D	$T_C=25^\circ C$	93	A
Continuous Drain Current (Package Limited)		$T_C=100^\circ C$	59	
		$T_C=25^\circ C$	60	
Drain to Source Voltage	V_{DS}	-	150	V
Gate to Source Voltage	V_{GS}	-	± 20	V
Pulsed Drain Current	I_{DM}	-	350	A
Avalanche Energy, Single Pulse	E_{AS}	$L=0.1mH, T_C=25^\circ C$	20	mJ
Power Dissipation	P_D	$T_C=25^\circ C$	125	W
Operating and Storage Temperature	T_J, T_{stg}	-	-55 to 150	$^\circ C$

Absolute Maximum Ratings

Parameter	Symbol	Max	Unit
Thermal Resistance Junction-Ambient	$R_{\theta JA}$	55	$^\circ C/W$
Thermal Resistance Junction-Case	$R_{\theta JC}$	1	$^\circ C/W$

Electrical Characteristics at $T_j=25^\circ\text{C}$ (unless otherwise specified)
Static Characteristics

Parameter	Symbol	Conditions	Value			Unit
			min	typ	max	
Drain to Source Breakdown Voltage	$V_{(\text{BR})\text{DSS}}$	$V_{\text{GS}}=0\text{V}, I_D=250\mu\text{A}$	150	-	-	V
Gate Threshold Voltage	$V_{\text{GS}(\text{th})}$	$V_{\text{GS}}=V_{\text{DS}}, I_D=250\mu\text{A}$	3	3.5	5	
Zero Gate Voltage Drain Current	I_{DSS}	$V_{\text{GS}}=0\text{V}, V_{\text{DS}}=150\text{V}, T_j=25^\circ\text{C}$	-	-	1	μA
		$V_{\text{GS}}=0\text{V}, V_{\text{DS}}=150\text{V}, T_j=100^\circ\text{C}$	-	-	100	
Gate to Source Leakage Current	I_{GSS}	$V_{\text{GS}}=\pm 20\text{V}, V_{\text{DS}}=0\text{V}$	-	-	± 100	nA
Drain to Source on Resistance	$R_{\text{DS}(\text{on})}$	$V_{\text{GS}}=15\text{V}, I_D=20\text{A}$	-	6	6.9	$\text{m}\Omega$
Drain to Source on Resistance	$R_{\text{DS}(\text{on})}$	$V_{\text{GS}}=10\text{V}, I_D=20\text{A}$	-	6.8	8.1	$\text{m}\Omega$
Transconductance	g_{fs}	$V_{\text{DS}}=5\text{V}, I_D=20\text{A}$	-	38	-	S
Gate Resistance	R_G	$V_{\text{GS}}=0\text{V}, V_{\text{DS}} \text{ Open}, f=1\text{MHz}$	-	1.2	-	Ω

Dynamic Characteristics

Input Capacitance	C_{iss}	$V_{\text{GS}}=0\text{V}, V_{\text{DS}}=75\text{V}, f=1\text{MHz}$	-	2534	-	pF
Output Capacitance	C_{oss}		-	1128	-	
Reverse Transfer Capacitance	C_{rss}		-	28	-	
Total Gate Charge	Q_g	$V_{\text{DD}}=75\text{V}, I_D=20\text{A}, V_{\text{GS}}=10\text{V}$	-	38	-	nC
Gate to Source Charge	Q_{gs}		-	13	-	
Gate to Drain (Miller) Charge	Q_{gd}		-	12	-	
Turn on Delay Time	$t_{\text{d}(\text{on})}$	$V_{\text{DD}}=75\text{V}, I_D=20\text{A}, V_{\text{GS}}=10\text{V}$	-	25	-	ns
Rise time	t_r		-	10	-	
Turn off Delay Time	$t_{\text{d}(\text{off})}$		-	32	-	
Fall Time	t_f		-	12	-	

Reverse Diode Characteristics

Diode Forward Voltage	V_{SD}	$V_{\text{GS}}=0\text{V}, I_F=20\text{A}$	-	0.93	1.2	V
Reverse Recovery Time	t_{rr}	$V_R=75\text{V}, I_F=20\text{A}, dI_F/dt=100\text{A}/\mu\text{s}$	-	68	-	ns
Reverse Recovery Charge	Q_{rr}		-	109	-	nC

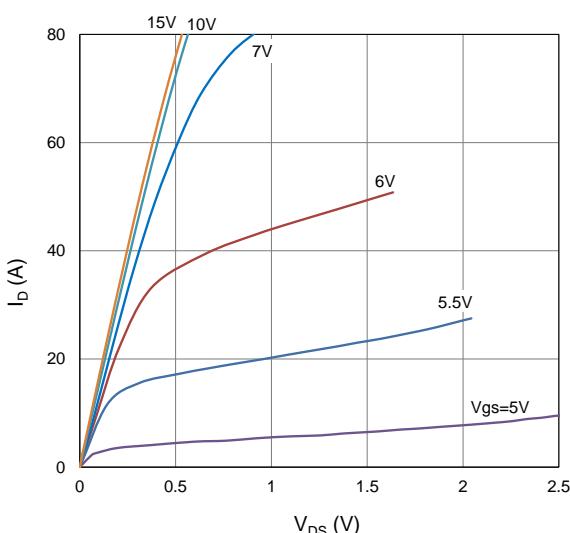
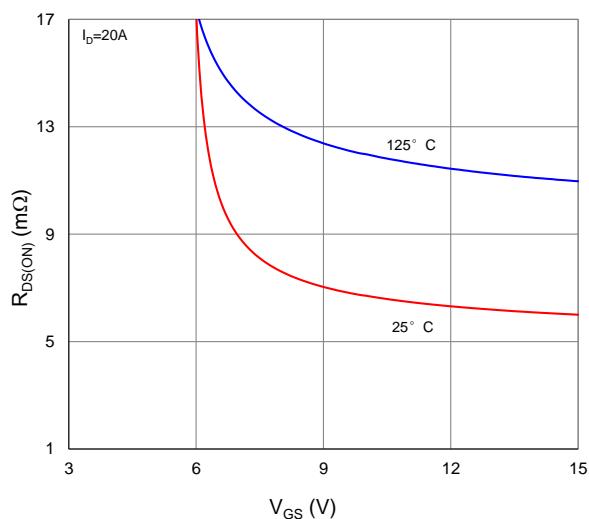
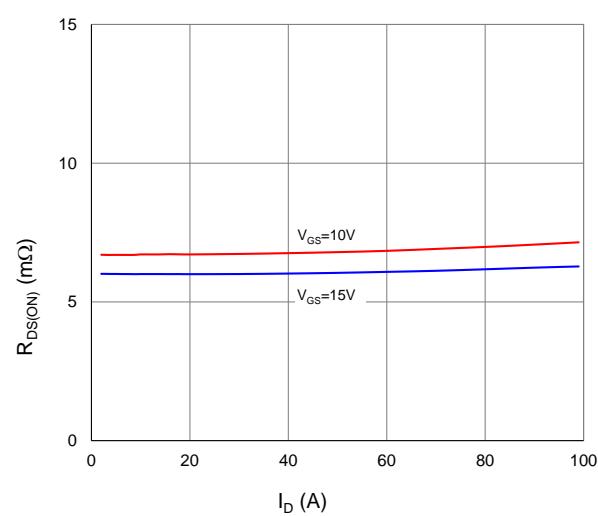
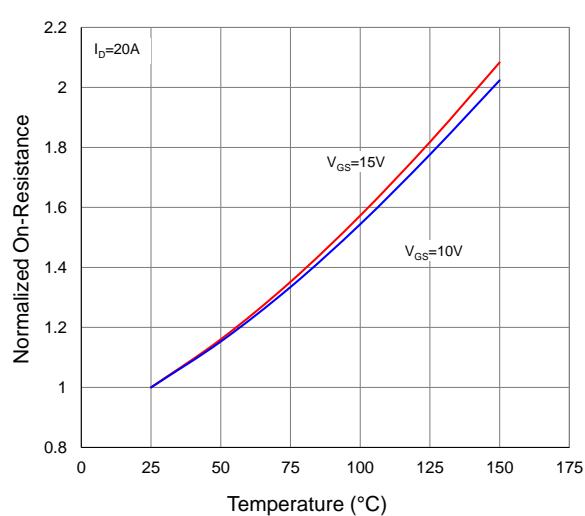
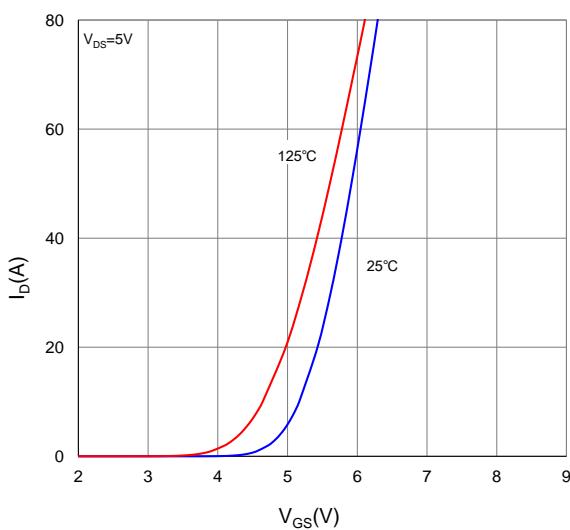
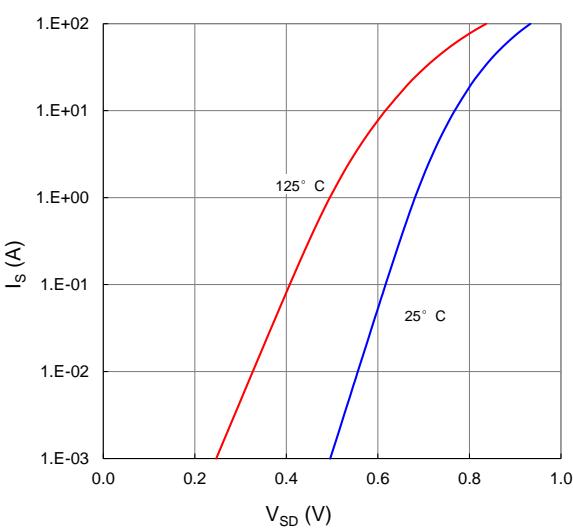
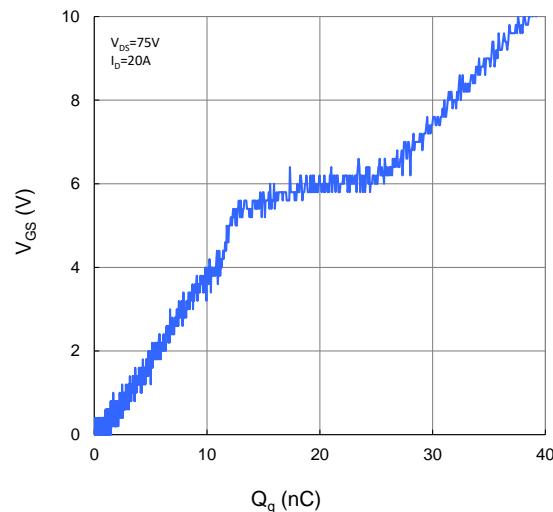
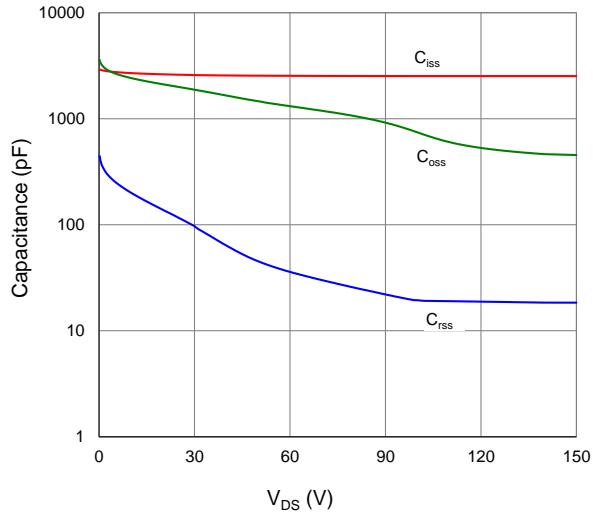
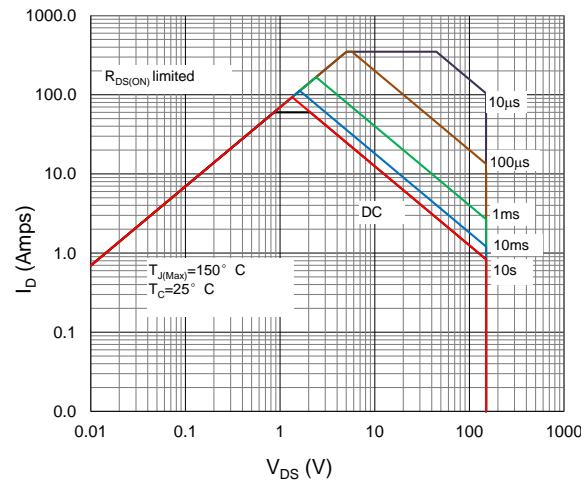
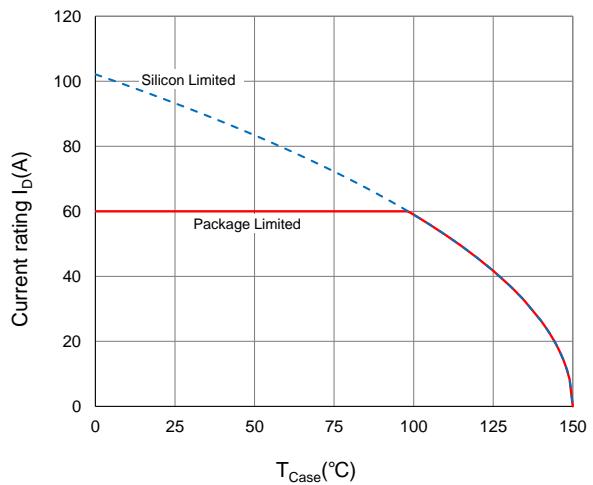
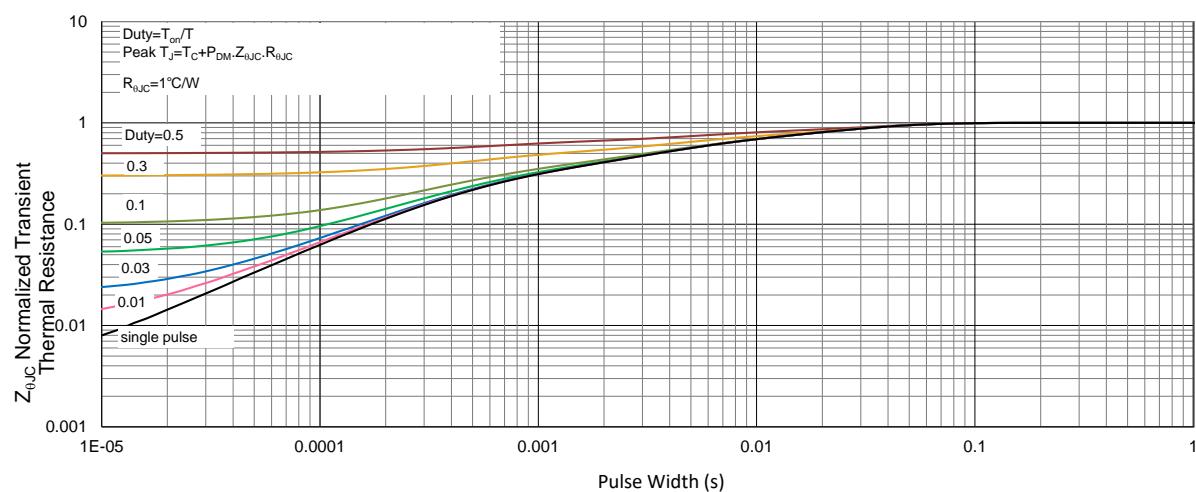
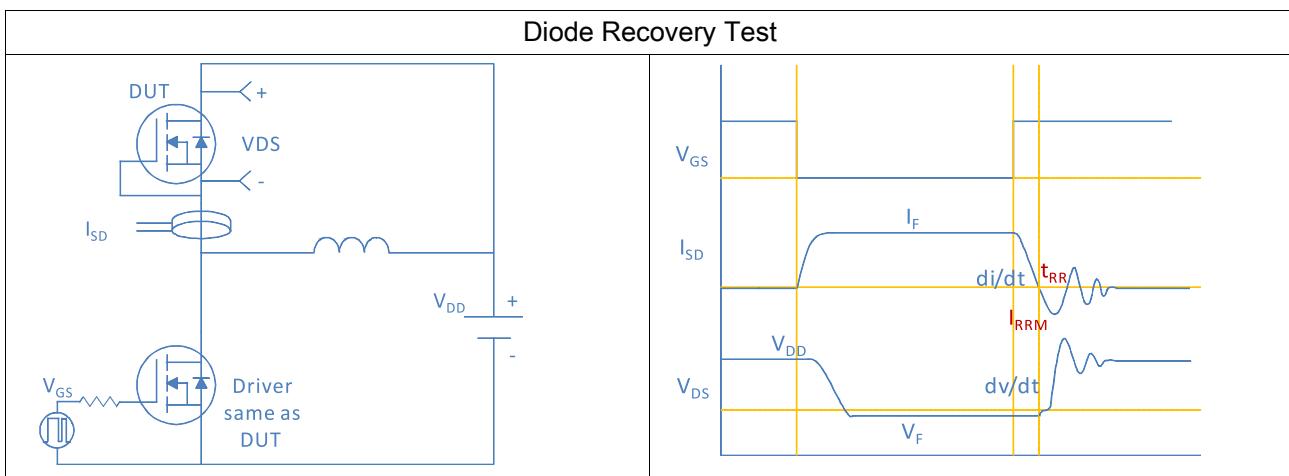
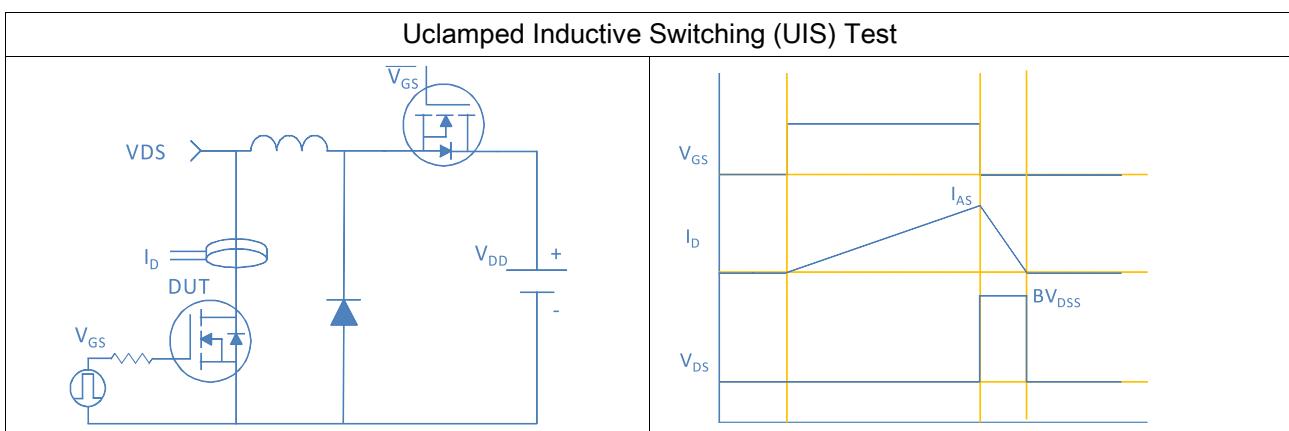
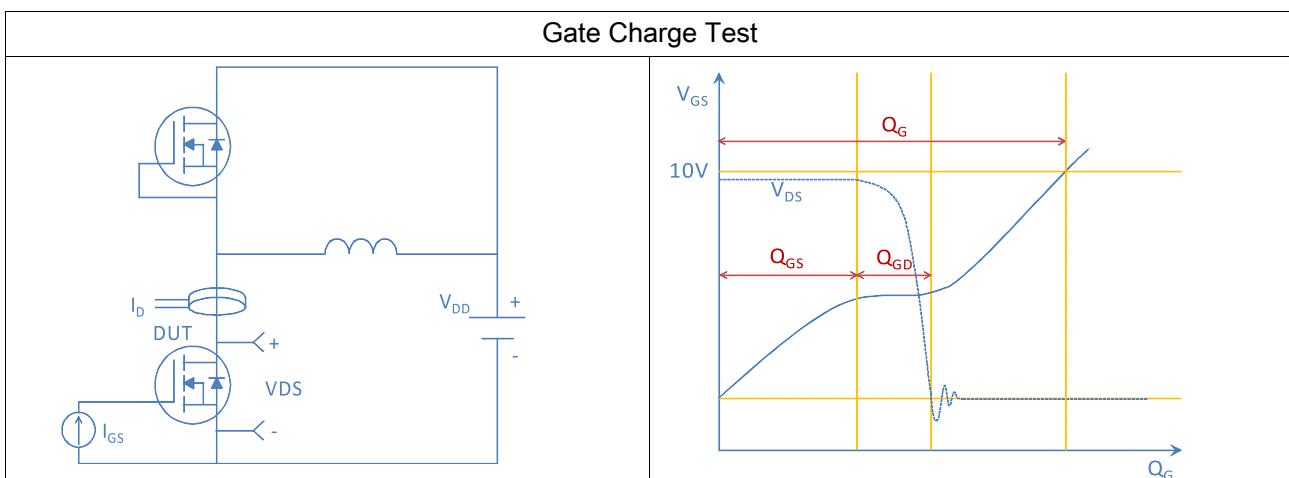
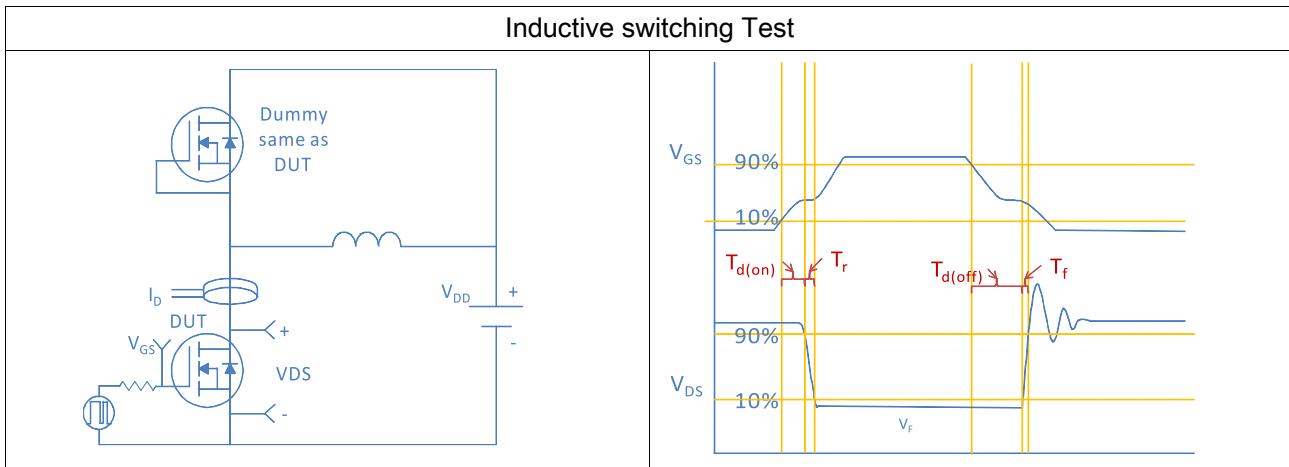
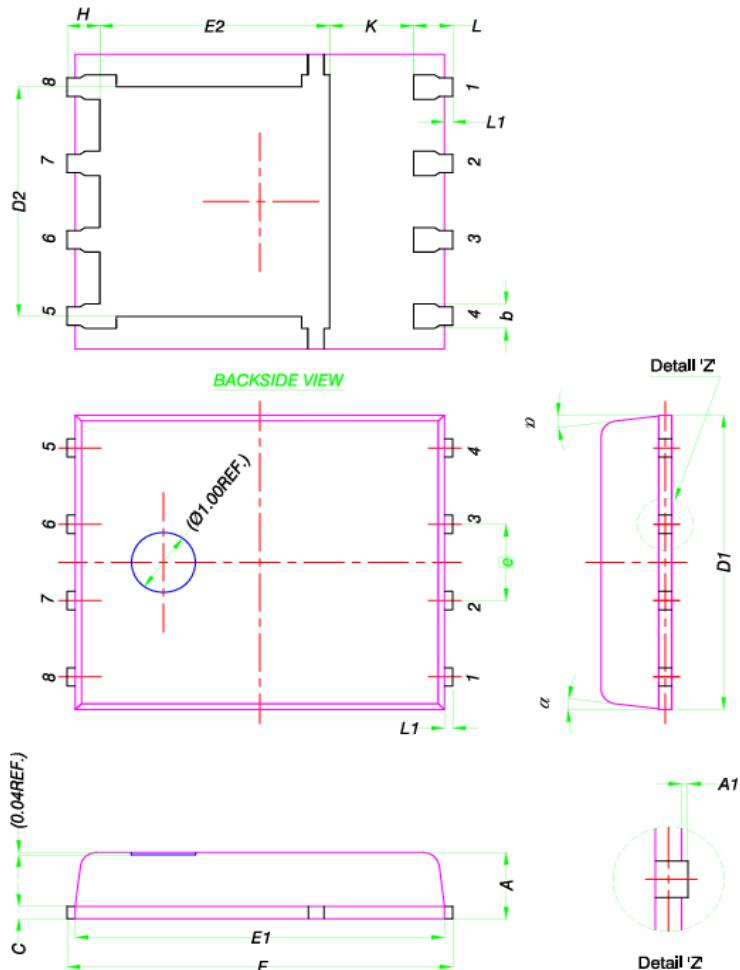
Fig 1. Typical Output Characteristics

Figure 2. On-Resistance vs. Gate-Source Voltage

Figure 3. On-Resistance vs. Drain Current and Gate Voltage

Figure 4. Normalized On-Resistance vs. Junction Temperature

Figure 5. Typical Transfer Characteristics

Figure 6. Typical Source-Drain Diode Forward Voltage


Figure 7. Typical Gate-Charge vs. Gate-to-Source Voltage

Figure 8. Typical Capacitance vs. Drain-to-Source Voltage

Figure 9. Maximum Safe Operating Area

Figure 10. Maximum Drain Current vs. Case Temperature

Figure 11. Normalized Maximum Transient Thermal Impedance, Junction-to-Case




Package Outline
DFN5x6_P, 8 Leads


DIM.	MILLIMETERS		
	MIN.	NOM.	MAX.
A	0.90	1.00	1.10
A1	0	-	0.05
b	0.33	0.41	0.51
C	0.20	0.25	0.30
D1	4.80	4.90	5.00
D2	3.61	3.81	3.96
E	5.90	6.00	6.10
E1	5.70	5.75	5.80
E2	3.38	3.58	3.78
(e) 1.27 BSC			
H	0.41	0.51	0.61
K	1.10	-	-
L	0.51	0.61	0.71
L1	0.06	0.13	0.20
α	0°	-	12°